

**4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY**
**Product Summary**

| V <sub>BR</sub> (Min) | I <sub>PP</sub> (Max) | C <sub>T</sub> (Typ) |
|-----------------------|-----------------------|----------------------|
| 6V                    | 5.5A                  | 0.55pF               |

**Description**

The DT1240-04LP20 is a high-performance device suitable for protecting four high speed I/Os. These devices are assembled in DFN2010-8 packages and have high ESD surge capability and low capacitance.

**Applications**

Typically used at high-speed ports such as USB2.0, USB3.0, IEEE1394 (Firewire<sup>®</sup>), iLink<sup>™</sup>, Serial ATA, DVI<sup>™</sup>, HDMI, PCI.

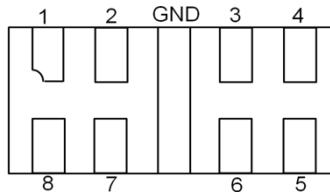
**Features**

- Clamping Voltage: 9V at 10A 100ns, TLP  
9.4V at 5.5A 8μs/20μs
- IEC 61000-4-2 (ESD): Air — ±16kV, Contact — ±14kV
- IEC 61000-4-5 (Lightning): ±5.5A (8/20μs)
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 0.55pF Typical
- TLP Dynamic Resistance: 0.25Ω
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**

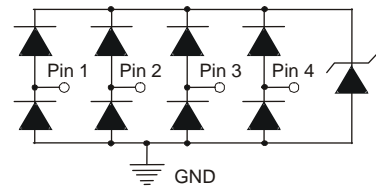
**Mechanical Data**

- Case: X2-DFN2010-8 (Type B)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Schematic
- Terminals: Finish – NiPdAu, Solderable per MIL-STD-202, Method 208 **e4**
- Weight: 0.025 grams (Approximate)

| Pin #      | Description   |
|------------|---------------|
| 1, 2, 3, 4 | I/O           |
| 5, 6, 7, 8 | No Connection |



Pin Description (Bottom View)



Device Schematic

**Ordering Information (Note 4)**

| Product         | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|-----------------|------------|---------|--------------------|-----------------|-------------------|
| DT1240-04LP20-7 | Standard   | MU4     | 7                  | 8               | 3,000/Tape & Reel |

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  - See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  - For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**

**MU4 YM**

MU4 = Product Type Marking Code  
YM = Date Code Marking  
Y = Year (ex: F = 2018)  
M = Month (ex: 9 = September)

**Date Code Key**

| Year | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 |
|------|------|------|------|------|------|------|
| Code | F    | G    | H    | I    | J    | K    |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | O   | N   | D   |

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic  | Symbol                   | Value       | Unit | Conditions                      |
|---|--------------------------|-------------|------|---------------------------------|
| Peak Pulse Current, per IEC 61000-4-5                 | I <sub>PP</sub>          | 5.5         | A    | I/O to V <sub>SS</sub> , 8/20μs |
| Peak Pulse Power, per IEC 61000-4-5                   | P <sub>PP</sub>          | 60          | W    | I/O to V <sub>SS</sub> , 8/20μs |
| ESD Protection – Contact Discharge, per IEC 61000-4-2 | V <sub>ESD_CONTACT</sub> | ±14         | kV   | I/O to V <sub>SS</sub>          |
| ESD Protection – Air Discharge, per IEC 61000-4-2     | V <sub>ESD_AIR</sub>     | ±16         | kV   | I/O to V <sub>SS</sub>          |
| Operating Temperature                                 | T <sub>OP</sub>          | -55 to +85  | °C   | —                               |
| Storage Temperature                                   | T <sub>STG</sub>         | -55 to +150 | °C   | —                               |

**Thermal Characteristics**

| Characteristic   | Symbol           | Value | Unit |
|--|------------------|-------|------|
| Power Dissipation Typical (Note 5)                       | P <sub>D</sub>   | 360   | mW   |
| Thermal Resistance, Junction to Ambient Typical (Note 5) | R <sub>θJA</sub> | 350   | °C/W |

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                    | Symbol             | Min  | Typ   | Max | Unit | Test Conditions   |
|-----------------------------------|--------------------|------|-------|-----|------|---|
| Reverse Working Voltage           | V <sub>RWM</sub>   | —    | —     | 5.5 | V    | I <sub>R</sub> =1mA, I/O to V <sub>SS</sub>               |
| Reverse Current                   | I <sub>R</sub>     | —    | —     | 0.5 | μA   | V <sub>R</sub> = 5V, I/O to V <sub>SS</sub>               |
| Reverse Breakdown Voltage         | V <sub>BR</sub>    | 6    | —     | —   | V    | I <sub>R</sub> = 1mA, I/O to V <sub>SS</sub>              |
| Forward Clamping Voltage          | V <sub>F</sub>     | -1.0 | -0.85 | —   | V    | I <sub>F</sub> = -15mA, I/O to V <sub>SS</sub>            |
| Reverse Clamping Voltage (Note 6) | V <sub>C</sub>     | —    | 9.4   | 11  | V    | I <sub>PP</sub> = 5.5A, I/O to V <sub>SS</sub> , 8/20μs   |
| ESD Clamping Voltage              | V <sub>ESD</sub>   | —    | 9     | —   | V    | TLP, 10A, t <sub>p</sub> = 100 ns, I/O to V <sub>SS</sub> |
| Dynamic Reverse Resistance        | R <sub>DIF-R</sub> | —    | 0.25  | —   | Ω    | TLP, 10A, t <sub>p</sub> = 100 ns, I/O to V <sub>SS</sub> |
| Dynamic Forward Resistance        | R <sub>DIF-F</sub> | —    | 0.25  | —   | Ω    | TLP, 10A, t <sub>p</sub> = 100 ns, V <sub>SS</sub> to I/O |
| Channel Input Capacitance         | C <sub>I/O</sub>   | —    | 0.55  | —   | pF   | V <sub>I/O</sub> = 2.5V, V <sub>SS</sub> = 0V, f = 1MHz   |

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.

6. Clamping voltage value is based on an 8x20μs peak pulse current (I<sub>PP</sub>) waveform.

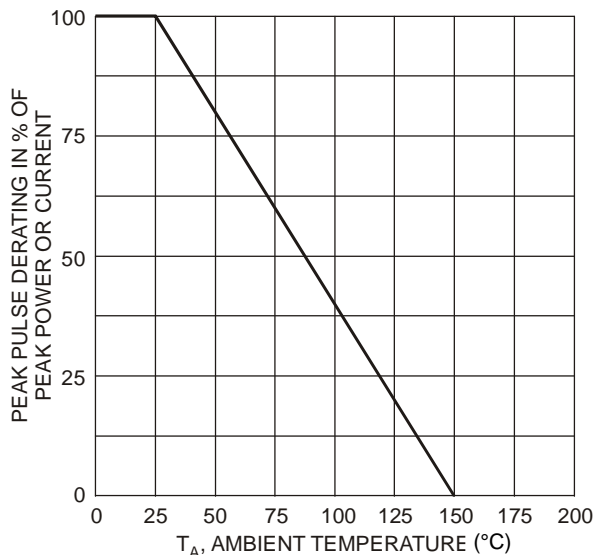


Figure 1 Pulse Derating Curve

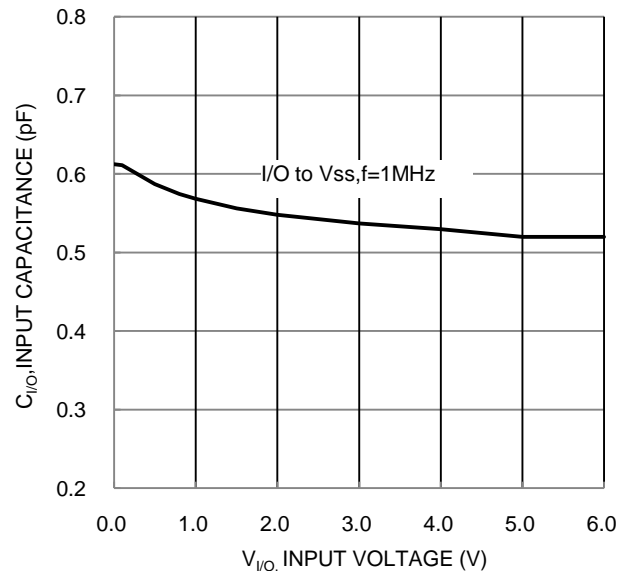


Figure 2 Input Capacitance vs. Input Voltage

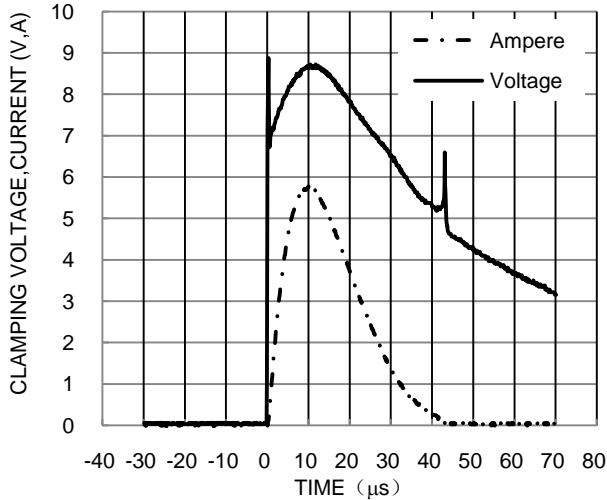


Figure 3. Waveform of Clamping Voltage, Current vs. Time (8/20 $\mu$ s, I/O to Vss)

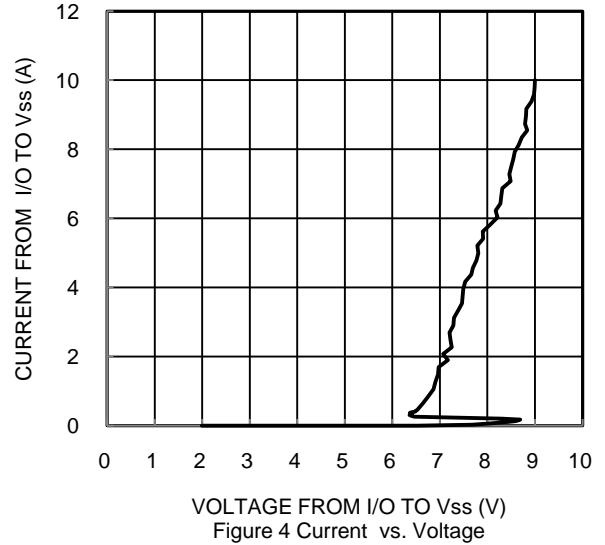
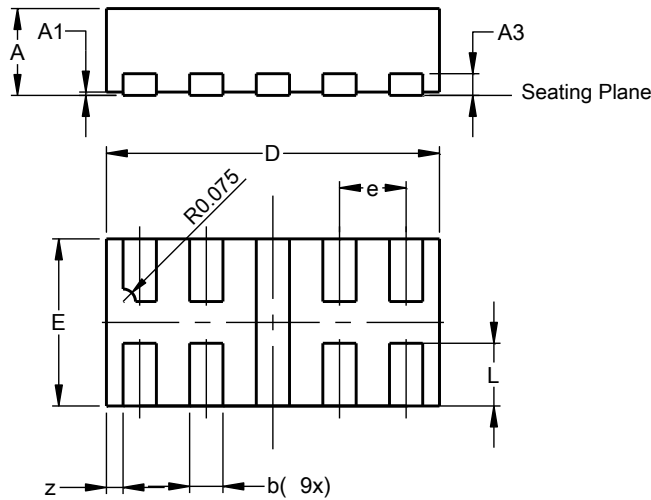


Figure 4 Current vs. Voltage

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### X2-DFN2010-8 (Type B)

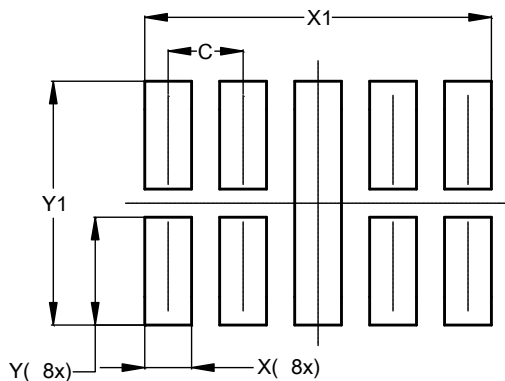


| X2-DFN2010-8<br>(Type B) |       |       |       |
|--------------------------|-------|-------|-------|
| Dim                      | Min   | Max   | Typ   |
| A                        | --    | 0.40  | --    |
| A1                       | 0.00  | 0.05  | 0.02  |
| A3                       | --    | --    | 0.13  |
| b                        | 0.15  | 0.25  | 0.20  |
| D                        | 1.950 | 2.075 | 2.000 |
| E                        | 0.950 | 1.075 | 1.000 |
| e                        | --    | --    | 0.40  |
| L                        | 0.325 | 0.425 | 0.375 |
| z                        | --    | --    | 0.10  |
| All Dimensions in mm     |       |       |       |

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version

### X2-DFN2010-8 (Type B)



| Dimensions | Value<br>(in mm) |
|------------|------------------|
| C          | 0.400            |
| X          | 0.250            |
| X1         | 1.850            |
| Y          | 0.575            |
| Y1         | 1.300            |

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#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.